



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **FUKASAWA, et al.**

Group Art Unit: **2814**

Serial No.: **09/029,608**

Examiner: **D. Graybill**

Filed: **May 15, 1998**

P.T.O. Confirmation No.: **6285**

For: **METHOD AND MOLD FOR MANUFACTURING SEMICONDUCTOR DEVICE, SEMICONDUCTOR**

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, Va 22313-1450

Date: May 6, 2003

Sir:

Prior to continued examination, please amend the above-captioned patent application as follows:

IN THE CLAIMS:

Please amend claims 109-111, 115, 119, 129 and 132 as follows:

109. (Three Times Amended) A semiconductor device comprising:
a semiconductor element having a surface on which protruding electrodes are formed;
a resin layer formed on the surface of the semiconductor element so as to seal the protruding electrodes except end portions thereof, said end portions protruding a height from the resin layer; and
external connection protruding electrodes provided to the end portions of the protruding